Materials Declaration

Package	CSP BGA
Body Size	6 X 6 mm
Ball Count	76
Option	96.5Sn/3Ag/0.5Cu
Ball Size	0.30 mm

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.20	3.40 E-02	391033
Epoxy resin	6.00	2.37 E-03	27218
Phenol Resin	6.00	2.37 E-03	27218
Metal Hydroxide	1.50	5.92 E-04	6805
Carbon Black	0.30	1.18 E-04	1361

Laminate

Item	% of Laminate	Weight (g)	PPM
BT Resin	75.00	2.61 E-02	300452
Solder Mask	21.60	7.53 E-03	86530
Copper	3.00	1.05 E-03	12018
Nickel	0.30	1.05 E-04	1202
Gold	0.10	3.49 E-05	401

Solder Ball

	% of Solder Ball	Weight (g)	PPM
Sn	96.50	7.68 E-03	88221
Ag	3.00	2.39 E-04	2743
Cu	0.50	3.98 E-05	457

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	7.33 E-04	8424

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	3.38 E-03	38826

Die Attach Material

Item	% of Die Attach	Weight (g)	PPM
Ag	70.0	4.32 E-04	4964
Functionalized ester	10.0	6.17 E-05	709
Diester	10.0	6.17 E-05	709
Polymeric resin	5.0	3.09 E-05	355
Epoxy Resin	5.0	3.09 E-05	355

Package Totals

Weight (g)	PPM
8.70 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	USEPA3050B. ICP-AES
Cd	Not Detected	EN 1122 Method B:2001. ICP-AES
Hg	Not Detected	USEPA 3052. ICP-AES
Cr+6	Not Detected	USEPA 3060A & USEPA 7196A
PBB	Not Detected	Analysis was performed by GC/MS
PBDE	Not Detected	Analysis was performed by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	5.00	US EPA Method 3052. ICP-OES
Cd	Not Detected	US EPA Method 3052. ICP-OES
Hg	Not Detected	US EPA Method 3052. ICP-OES
Cr+6	Not Detected	US EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	Analysis was performed by GC/MS
PBDE	Not Detected	Analysis was performed by GC/MS

Laminate

Item	PPM	Method
Pb	Not Detected	US EPA Method 3052. ICP-OES
Cd	Not Detected	US EPA Method 3052. ICP-OES
Hg	Not Detected	US EPA Method 3052. ICP-OES
Cr+6	Not Detected	US EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	Analysis was performed by GC/MS
PBDE	Not Detected	Analysis was performed by GC/MS

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES